

Elpida, PTI, and UMC partner on 3D IC integration development for advanced technologies including 28nm

I-Micronews

Elpida Memory Inc., Powertech Technology Inc. (PTI), and United Microelectronics Corporation (NYSE: UMC; TSE: 2303) ("UMC"), today announced that they have finalized the 3-way tie-up to deliver 3DIC integration technologies for advanced processes including 28 nanometer (nm). UMC and PTI engineers have already been working with Elpida on joint development of TSV products at Elpida's Hiroshima Plant. This collaboration leverages the strengths of Elpida's DRAM, PTI's assembly, and UMC's foundry logic technologies to develop a one-chip 3D IC Logic+DRAM integration solution.

[SOURCE](#) [1]

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